National Semiconductor

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LM4431
Micropower Shunt Voltage Reference

General Description

Ideal for space critical applications, the LM4431 voltage reference is available in the sub-miniature (3 mm x 1.3 mm) SOT-23 surface-mount package. The LM4431's advanced design eliminates the need for an external stabilizing capacitor while ensuring stability with any capacitive load, thus making the LM4431 easy to use. The operating current range is 100 µA to 15 mA.

The LM4431 utilizes fuse and zener-zap reverse breakdown voltage trim during wafer sort to ensure that the parts have an accuracy of better than ±2.0% at 25˚C. Bandgap reference temperature drift curvature correction and low dynamic impedance ensure stable reverse breakdown voltage accuracy over a wide range of operating temperatures and currents.

Features

- Small package: SOT-23
- No output capacitor required
- Tolerates capacitive loads
- Fixed reverse breakdown voltage of 2.50V

Key Specifications

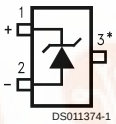
- Output voltage tolerance 25˚C: ±2.0% (max)
- Low output noise (10 Hz to 10 kHz): 35 μV_{rms} (typ)
- Wide operating current range: 100 µA to 15 mA
- Commercial temperature range: 0˚C to +70˚C
- Low temperature coefficient: 30 ppm/˚C (typ)

Applications

- Portable, Battery-Powered Equipment
- Data Acquisition Systems
- Instrumentation
- Process Control
- Energy Management
- Product Testing
- Power Supplies

Connection Diagram

SOT-23



* This pin must be left floating or connected to pin 2.

Top View
Order Number LM4431M3-2.5
See NS Package Number M03B
(JEDEC Registration TO-236AB)

SOT-23 Package Marking Information

Only three fields of marking are possible on the SOT-23's small surface. The following table gives the meaning of the three fields.

Part Marking	Field Definition
S2E	First Field: S = Reference Second Field: 2 = 2.500V Voltage Option Third Field: E = Initial Reverse Breakdown Voltage Tolerance of ±2.0%

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Reverse Current	20 mA
Forward Current	10 mA
Power Dissipation (T_A = 25˚C) (Note 2)	
M3 Package	306 mW
Storage Temperature	−65˚C to +150˚C
Lead Temperature	
M3 Package	
Vapor phase (60 seconds)	+215˚C
Infrared (15 seconds)	+220˚C

ESD Susceptibility

Human Body Model (Note 3)	2 kV
Machine Model (Note 3)	200V

See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.

Operating Ratings (Notes 1, 2)

Temperature Range	
($T_{min} \le T_A \le T_{max}$)	$0˚C \le T_A \le +70˚C$
Reverse Current	
LM4431-2.5	100 µA to 15 mA

LM4431-2.5

Electrical Characteristics

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX}; all other limits $T_A = T_J$ = 25˚C.

Symbol	Parameter	Conditions	Typical (Note 4)	LM4431M3 Limits (Note 5)	Units (Limit)
V_R	Reverse Breakdown Voltage	I_R = 100 µA	2.500		V
	Reverse Breakdown VoltageTolerance	I_R = 100 µA		±50	mV (max)
I_{RMIN}	Minimum Operating Current		45		µA
				100	µA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I_R = 10 mA	±30		ppm/˚C
	Voltage Temperature	I_R = 1 mA	±30		ppm/˚C
	Coefficient	I_R = 100 µA	±30		ppm/˚C
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage	$I_{RMIN} \le I_R \le$ 1 mA	0.4		mV
	Change with Operating			1.0	mV (max)
	Current Change			**1.2**	mV (max)
		1 mA $\le I_R \le$ 15 mA	2.5		mV
				8.0	mV (max)
				25	mV (max)
Z_R	Reverse Dynamic Impedance	I_R = 1 mA, f = 120 Hz $I_{AC} = 0.1\ I_R$	1.0		Ω
e_N	Wideband Noise	I_R = 100 µA 10 Hz ≤ f ≤ 10 kHz	35		μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25˚C ±0.1˚C I_R = 100 µA	120		ppm

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 2: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $PD_{max} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4431, T_{Jmax} = 125˚C, and the typical thermal resistance (θ_{JA}), when board mounted, is 326˚C/W for the SOT-23 package.

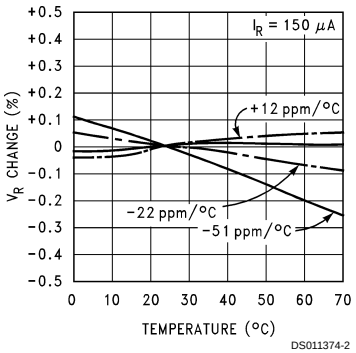
Note 3: The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin.

Note 4: Typicals are at T_J = 25˚C and represent most likely parametric norm.

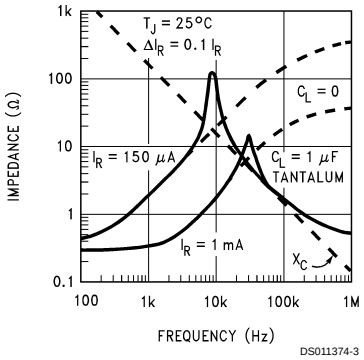
Note 5: Limits are 100% production tested at 25˚C. Limits over temperature are guaranteed through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.

Typical Performance Characteristics

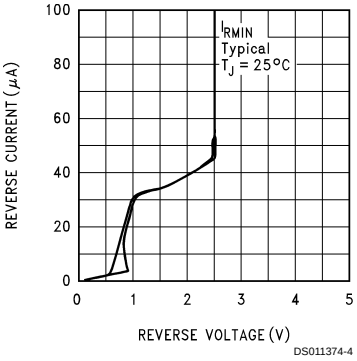
Temperature Drift for Different Average Temperature Coefficient



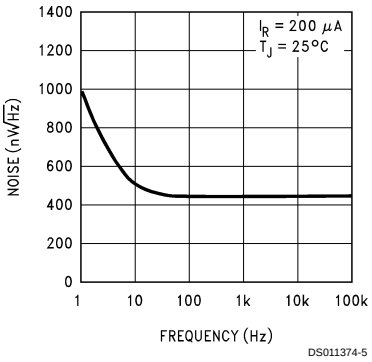
Output Impedance vs Frequency



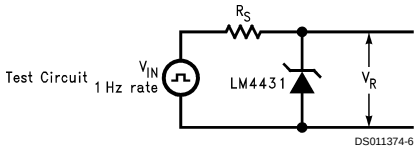
Reverse Characteristics and Minimum Operating Current



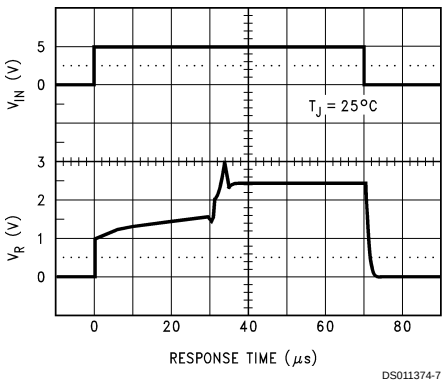
Noise Voltage



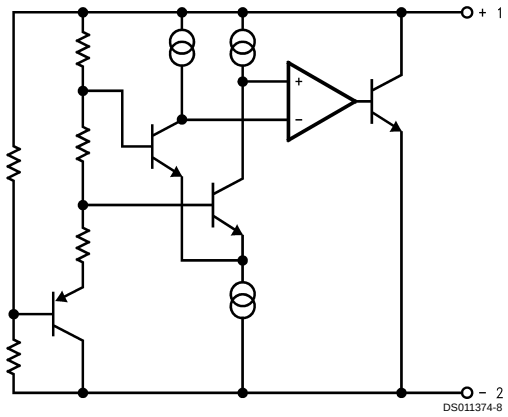
Start-Up Characteristics



LM4431-2.5 R_S = 30k



Functional Block Diagram



Applications Information

The LM4431 is a micro-power curvature-corrected 2.5V bandgap shunt voltage reference. For space critical applications, the LM4431 is available in the sub-miniature SOT-23 surface-mount package. The LM4431 has been designed for stable operation without the need of an external capacitor connected between the "+" pin and the "−" pin. If, however, a bypass capacitor is used, the LM4431 remains stable. The operating current range is 100 µA to 15 mA.

The LM4431's SOT-23 package has a parasitic Schottky diode between pin 2 (−) and pin 3 (Die attach interface contact). Therefore, pin 3 of the SOT-23 package must be left floating or connected to pin 2.

In a conventional shunt regulator application (*Figure 1*) , an external series resistor (R_S) is connected between the supply voltage and the LM4431. R_S determines the current that flows through the load (I_L) and the LM4431 (I_Q). Since load current and supply voltage may vary, R_S should be small enough to supply at least the minimum acceptable I_Q to the LM4431 even when the supply voltage is at its minimum and the load current is at its maximum value. When the supply voltage is at its maximum and I_L is at its minimum, R_S should be large enough so that the current flowing through the LM4431 is less than 15 mA.

R_S is determined by the supply voltage, (V_S), the load and operating current, (I_L and I_Q), and the LM4431's reverse breakdown voltage, V_R.

$$R_S = \frac{V_S - V_R}{I_L + I_Q}$$

Typical Applications

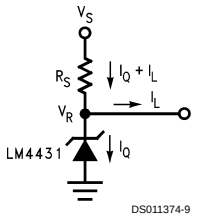


FIGURE 1. Shunt Regulator

Typical Applications (Continued)

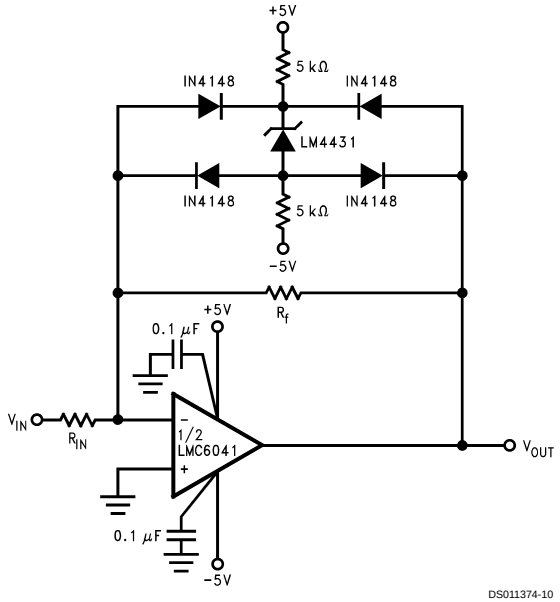


FIGURE 2. Bounded amplifier reduces saturation-induced delays and can prevent succeeding stage damage. Nominal clamping voltage is ±3.9V (LM4431's reverse breakdown voltage +2 diode V_F).

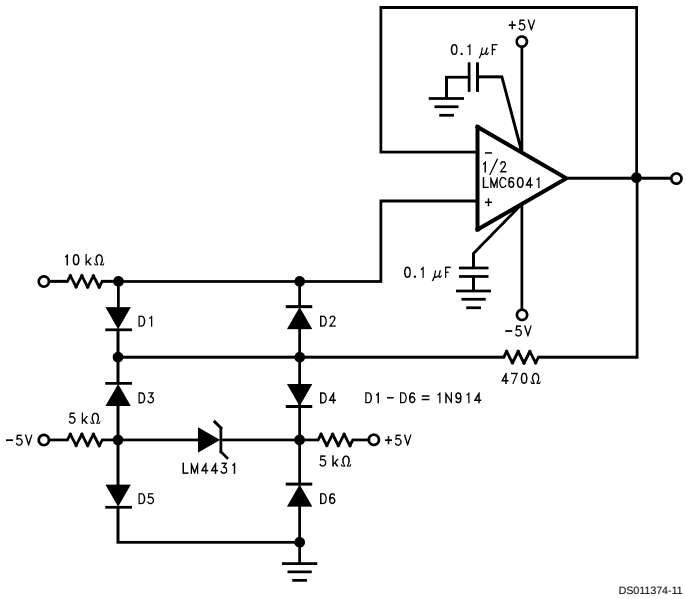
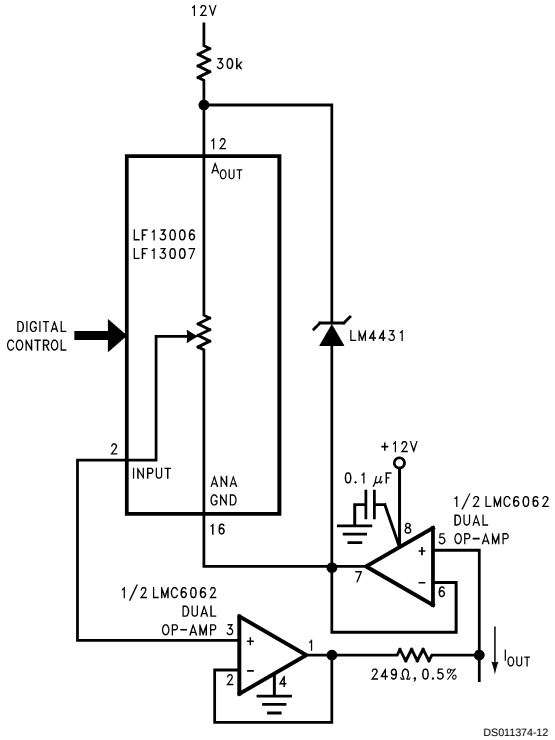


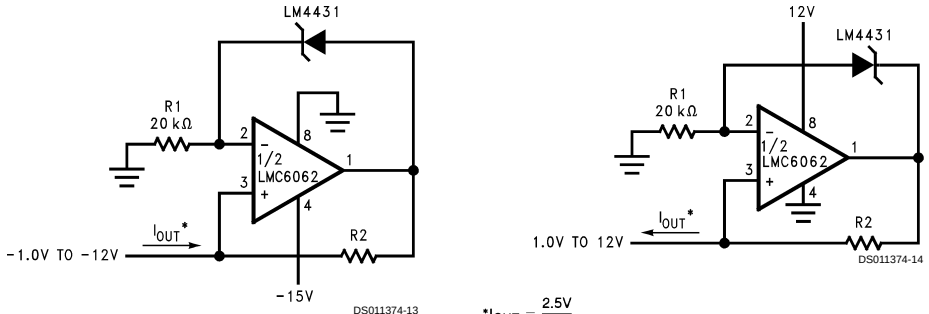
FIGURE 3. Protecting Op Amp input. The bounding voltage is ±4V with the LM4431 (LM4431's reverse breakdown voltage + 3 diode V_F).

Typical Applications (Continued)



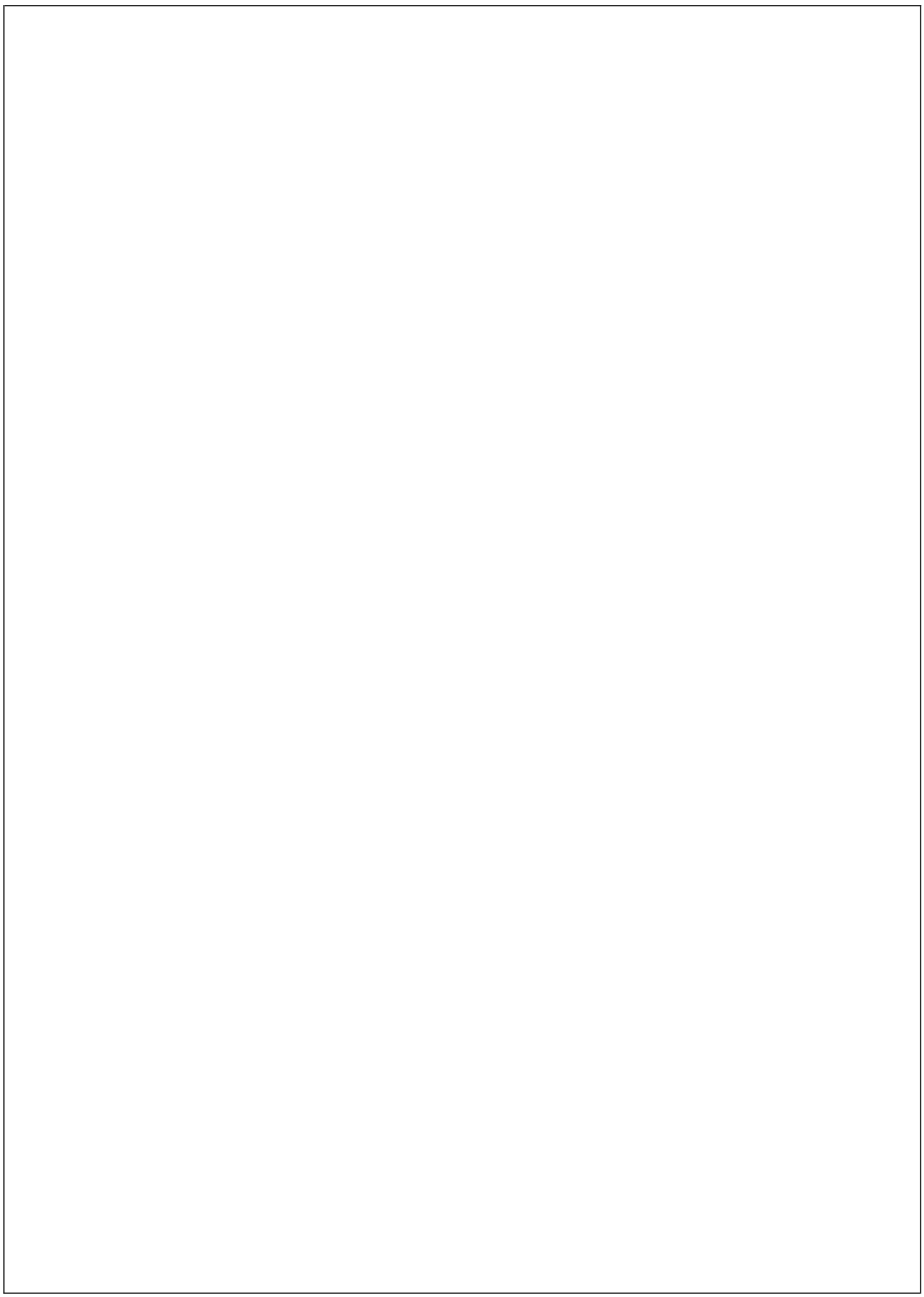
$$I_{OUT} = \frac{2.5V}{249\Omega}\left[\frac{1}{\text{gain set \#}}\right]$$

FIGURE 4. Programmable Current Source

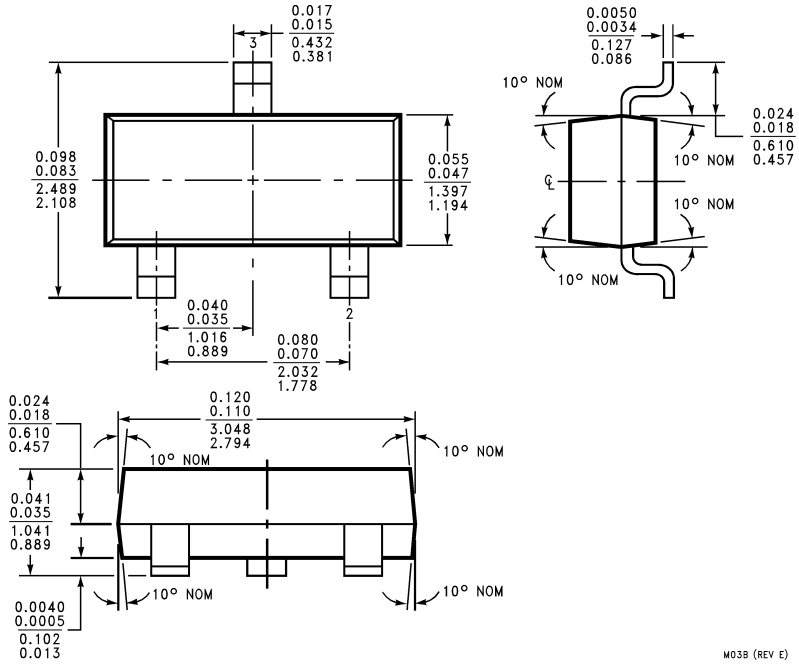


$$*I_{OUT} = \frac{2.5V}{R2}$$

FIGURE 5. Precision 1 µA to 1 mA Current Sources



Physical Dimensions inches (millimeters) unless otherwise noted



Plastic Surface Mount Package (M3)
NS Package Number M03B
(JEDEC Registration TO-236AB)

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